"RESIDE UNDER 37 CFR 1.116-EXPENDED PROCEDURE EXAMINING GROUP\_ 7 & 1\"

204612US-2

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

:

YUUICHI HIRANO ET AL.

: EXAMINER: TRAN, T.

SERIAL NO: 09/802,886

FILED: MARCH 12, 2001

: GROUP ART UNIT: 2811

FOR: SEMICONDUCTOR DEVICE AND

METHOD OF MANUFACTURING

THE SAME

JAN 22 2003
ECHNOLOGY CENTER 2800

## **RESPONSE**

ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

SIR:

In response to the Office Action of November 8, 2002, please amend the aboveidentified application as follows:

## IN THE CLAIMS

Please amend independent Claim 1 to read as follows:1

5087

1. (Twice Amended) A semiconductor device comprising:

an SOI substrate having a structure in which a semiconductor substrate, an insulating

layer and a semiconductor layer are layered in this order;

a partial-isolation insulating film formed in a main surface of said semiconductor

layer;

<sup>&</sup>lt;sup>1</sup>A marked-up copy of the amendments is attached hereto.